

ABSTRACT OF THE DISCLOSURE

One via contact through which upper and lower interconnections of a multilevel interconnection are connected to each other is provided when the width or  
5 volume of the lower interconnection is not larger than a given value. A plurality of via contacts are arranged at regular intervals, each of which is not larger than a given value, in an effective diffusion region of voids included in the lower interconnection,  
10 when the width or volume of the lower interconnection exceeds a given value.